

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A releasing layer transfer film for forming a releasing layer onto an insulating layer serving as a component of a COF flexible printed wiring board, characterized in that the releasing layer transfer film comprises a transfer film substrate, and a transferable releasing layer provided on a surface of the transfer film substrate, wherein the transferable releasing layer is formed from a releasing agent comprising a silazane compound and can be transferred onto the insulating layer.

Claims 2-7. (canceled)

8. (currently amended): A releasing layer transfer film according to claim 1-5, wherein the transferable releasing layer is formed by applying a solution of the releasing agent onto the transfer film substrate, and heating.

9. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, wherein the transferable releasing layer is transferred by firmly affixing the transferable releasing layer to the insulating layer, followed by heating.

10. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, wherein the transferable releasing layer is provided on a surface of the transfer film substrate continuously or in the form of dispersed islands.

11. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, wherein the transferable releasing layer is transferred onto the insulating layer continuously or in the form of dispersed islands.

12. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, wherein the transferable releasing layer is provided so as to correspond to a region for forming ~~the~~ a wiring pattern, the region intervening in at least two rows of sprocket holes of the COF flexible printed wiring board.

13. (currently amended): A releasing layer transfer film according to claim 12, wherein the COF flexible wiring board has at least two rows of wiring-pattern-formed regions, and the transferable releasing layer ~~is provided such that is shaped into a plurality of stripes of the layer~~ strips corresponding to the wiring patterns.

14. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, which has, ~~between the transfer film substrate and the transferable releasing layer,~~ an adhesion layer ~~that can be exclusively released from the transferable releasing layer~~ between the transfer film substrate and the transferable releasing layer.

15. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, wherein the transfer film substrate is affixed onto the insulating layer so as to serve as a reinforcing film during a production step of the COF flexible printed wiring board.

16. (currently amended): A releasing layer transfer film according to ~~any of claims 1 to 8~~ claim 1, which has, on a surface of the transferable releasing layer, a peelable film that can be peeled from the transferable releasing layer.

17. (currently amended): A laminate film, ~~characterized in that the laminate film comprises~~ comprising a film substrate, a releasing layer provided on a surface of the film substrate, ~~and~~ an insulating layer provided on the surface of the releasing layer opposite the side of the film substrate, and a conductor layer provided on the surface of the insulating layer opposite the side of the releasing layer, wherein the releasing layer is formed from a releasing agent containing at least one species selected from a silane compound and silica sol, and the insulating layer serves as a member of a COF flexible printed wiring board.

18. (original): A laminate film according to claim 17, wherein the releasing layer is formed from a releasing agent containing a silazane compound.

19. (canceled)

20. (currently amended): A laminate film according to claim 17, which has, ~~between the film substrate and the releasing layer~~, an adhesion layer between the film substrate and the releasing layer ~~that can be exclusively released from the releasing layer~~.

Claims 21-24. (canceled)

25. (new): A method for producing a COF flexible printed wiring board, the method comprising

laminating, onto an insulating layer serving as a component of a COF flexible printed wiring board, a releasing layer transfer film comprising a transfer film substrate, and a transferable releasing layer provided on a surface of the transfer film substrate, such that the transferable releasing layer is laminated on the insulating layer;

forming a wiring pattern in the conductor layer provided on the surface of the insulating layer opposite the surface on which the releasing layer transfer film has been laminated to thereby produce a COF flexible printed wiring board; and

peeling the transfer film substrate, to thereby transfer the transferable releasing layer onto the insulating layer, whereby a COF flexible printed wiring board having a releasing layer on the insulating layer is produced.

26. (new): A method for producing a COF flexible printed wiring board according to claim 25, wherein the releasing layer is transferred onto the insulting layer through heating during the course of peeling of the film substrate.

27. (new): A method for producing a COF flexible printed wiring board according to claim 25, wherein the releasing layer is transferred onto a surface of the insulating layer continuously or in the form of dispersed islands.